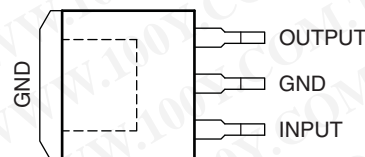
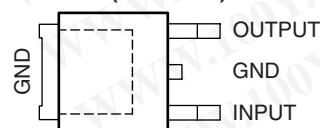


LOW-DROPOUT FIXED-VOLTAGE REGULATORS

 Check for Samples: [TL760M33-Q1](#)

FEATURES

- Qualified for Automotive Applications
- $\pm 3\%$ Output Voltage Variation Across Load and Temperature
- Load-Dump Protection
- 500-mV Maximum Dropout Voltage at 500 mA
- Fixed 3.3-V Output
- Internal Thermal-Overload Protection
- Internal Overvoltage Protection
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval

**KTT (TO-263) PACKAGE
(TOP VIEW)**

**KVU (TO-252) PACKAGE
(TOP VIEW)**


DESCRIPTION/ORDERING INFORMATION

The TL760M33-Q1 low-dropout regulator offers a variety of fixed-voltage options that offer a maximum continuous input voltage of 26 V. Utilizing a pnp pass element, this regulator is capable of sourcing 500 mA of current, with a specified maximum dropout of 500 mV, making the TL760M33-Q1 ideal for low-voltage applications. Additionally, the TL760M33-Q1 regulator offers very tight output accuracy of $\pm 3\%$ across operating load and temperature ranges. Other convenient features the regulators provide are internal overcurrent limiting, thermal-overload protection, and overvoltage protection. The TL760M33-Q1 is load-dump protected to its maximum operating condition of 45 V. Stability has been optimized for typical automotive applications and low-cost capacitors.

ORDERING INFORMATION⁽¹⁾

T_A	V_O (TYP)	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	3.3 V	TO-263 – KTT	Reel of 500	TL760M33QKTRRQ1	TL760M33Q1
		TO-252 – KVU	Reel of 2500	TL760M33QKVURQ1	760M33Q1

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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TL760M33-Q1

SGLS284I – OCTOBER 2005 – REVISED DECEMBER 2010

www.ti.com

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating virtual junction temperature range (unless otherwise noted)

V _I	Maximum input voltage	45 V
T _J	Operating virtual junction temperature	150°C
T _{stg}	Storage temperature range	–65°C to 150°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

PACKAGE THERMAL DATA⁽¹⁾

PACKAGE	BOARD	θ _{JA}
TO-252 (KVU)	High K, JESD 51-5	30.3°C/W
TO-263 (KTT)	High K, JESD 51-5	26.9°C/W

- (1) Maximum power dissipation is a function of T_{J(max)}, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_{J(max)} – T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can impact reliability.

THERMAL RESISTANCE

1-oz copper, one-layer PCB

THERMAL RESISTANCE	VALUE
R _{JA}	55°C/W (area = 240 mm ²)
R _{JC}	5.5°C/W from FET to tab
R _{JC}	0.1°C/W from die center to tab

RECOMMENDED OPERATING CONDITIONS

	MIN	MAX	UNIT
V _I Input voltage	3.8	26	V
I _O Output current	0	500	mA
T _J Operating virtual-junction temperature	–40	150	°C

ELECTRICAL CHARACTERISTICS

V_I = 6 V, I_O = 500 mA, T_J = –40°C to 150°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN	TYP	MAX	UNIT
V _O Output voltage	I _O = 5 mA to 500 mA, V _I = 3.8 V to 26 V, T _J = 125°C	3.2	3.3	3.4	V
	T _J = 150°C, I _O = 5 mA to 300 mA, V _I = 3.8 V to 26 V	3.2	3.3	3.4	
I _Q Current consumption, I _Q = I _I – I _O	V _I = 6 V	I _O = 250 mA		8	mA
		I _O = 500 mA		20	
Line regulation	V _I = 3.8 V to 28 V			10	mV
PSRR Power-supply ripple rejection	f = 100 Hz, V _{ripple} = 0.5 V _{PP} , V _I = 6 V			62	dB
Load regulation	I _O = 5 mA to 500 mA			5	mV
V _{DO} Dropout voltage ⁽²⁾	I _O = 250 mA			400	mV
	I _O = 500 mA			500	

- (1) Pulse-testing techniques are used to maintain the virtual junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-μF capacitor across the input and a 22-μF tantalum capacitor, with equivalent series resistance of 1.5 Ω on the output.
- (2) Measured when the output voltage, V_O, has dropped 100 mV from the nominal value obtained when V_I = 6 V

COMPENSATION-CAPACITOR SELECTION INFORMATION

The TL760M is a low-dropout regulator. This means that the capacitance loading is important to the performance of the regulator because it is a vital part of the control loop. The capacitor value and the equivalent series resistance (ESR) both affect the control loop and must be defined for the load range. Figure 1 can be used to establish the capacitance value and ESR range for the best regulator performance.

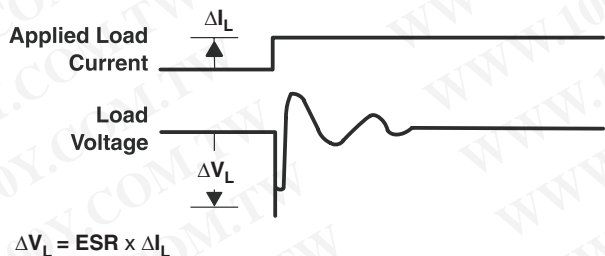
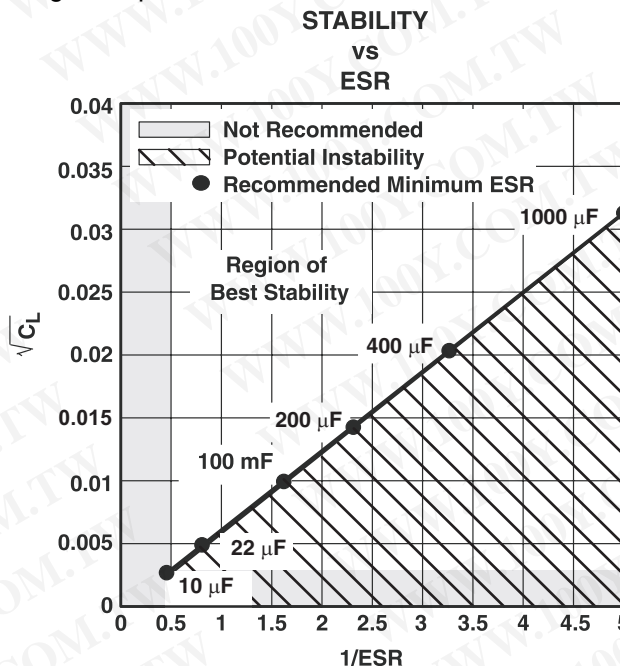
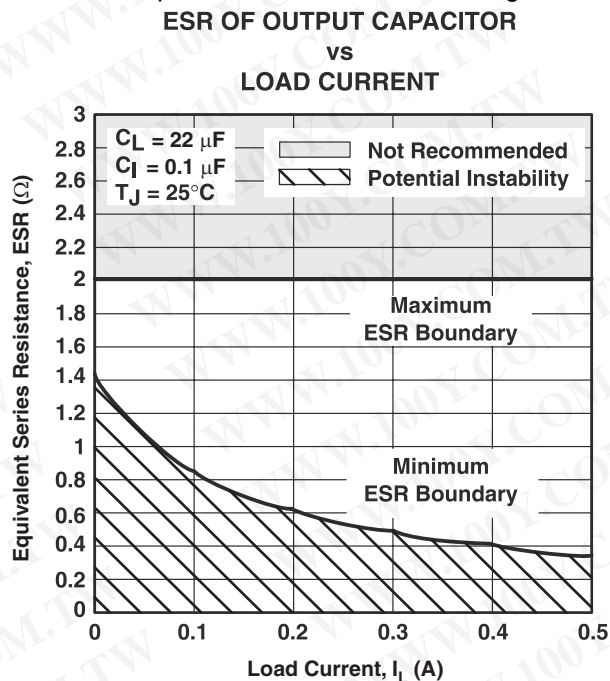


Figure 1.

Figure 2.

TYPICAL APPLICATION SCHEMATIC

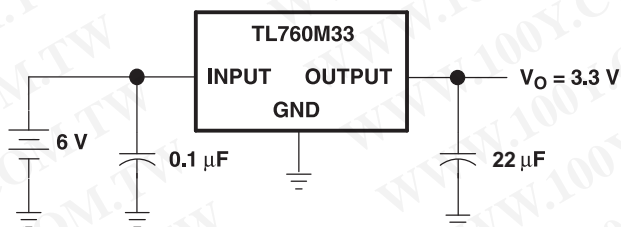


Figure 3.

TYPICAL CHARACTERISTICS

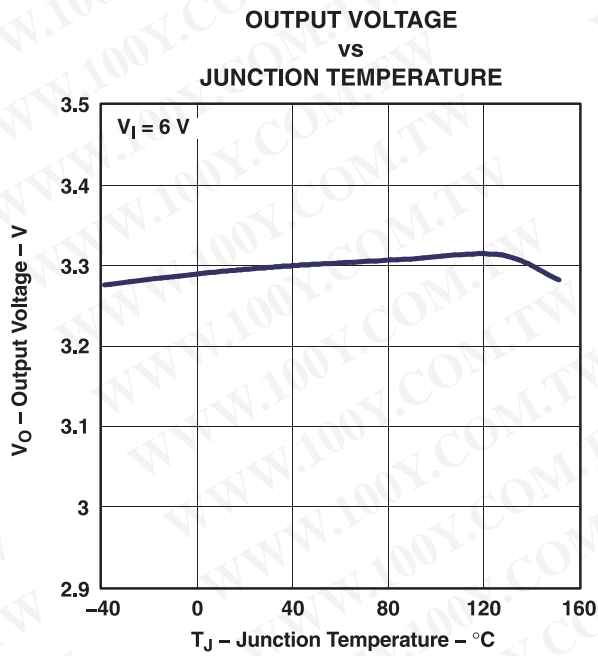


Figure 4.

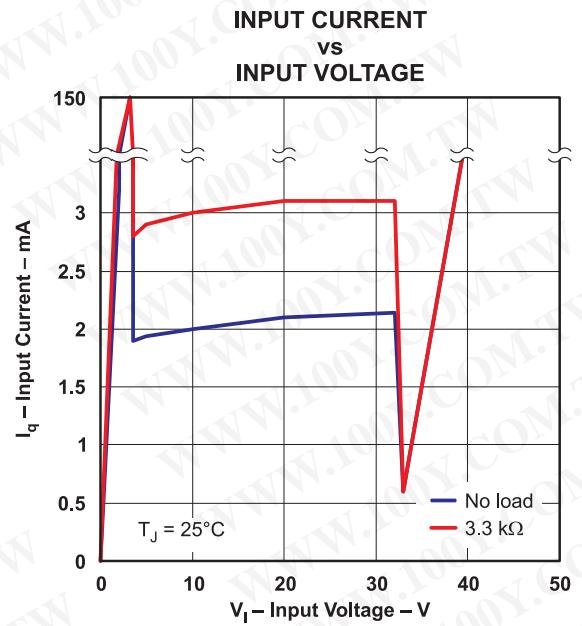


Figure 5.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TL760M33QKTTTRQ1	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR	-40 to 125	TL760M33Q1	Samples
TL760M33QKVURQ1	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 125	760M33Q1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

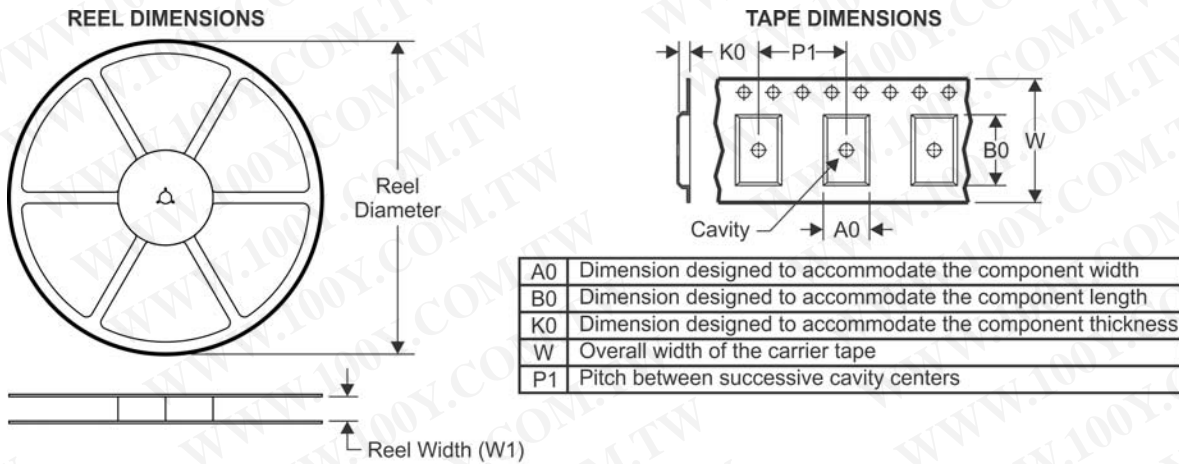
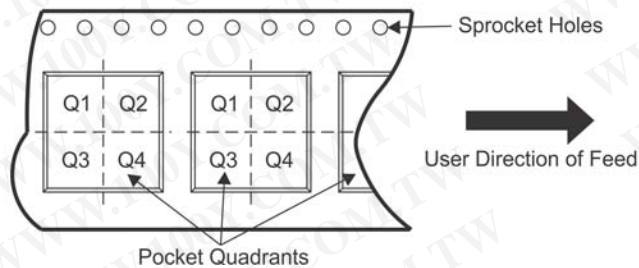
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

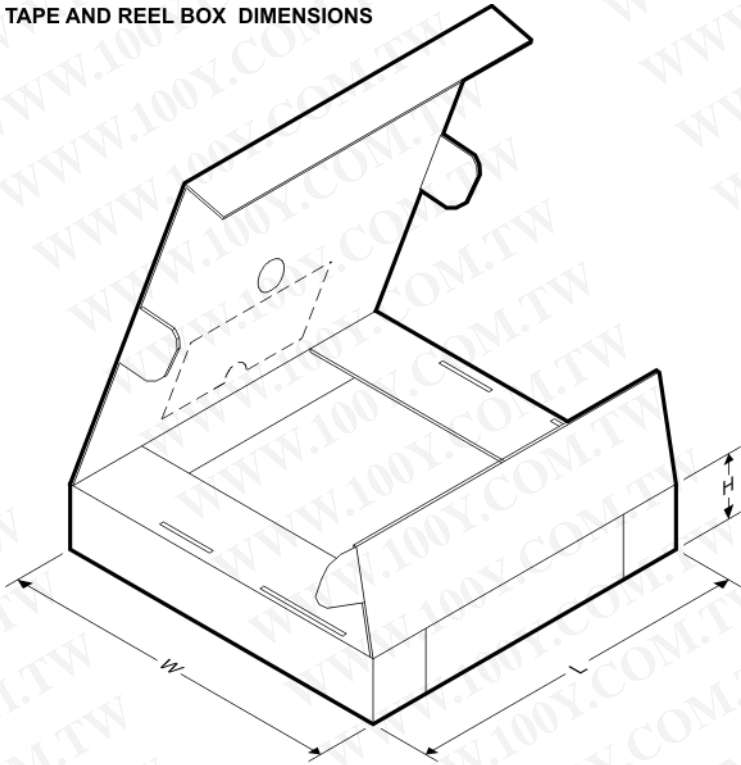
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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL760M33QKVURQ1	PFM	KVU	3	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2

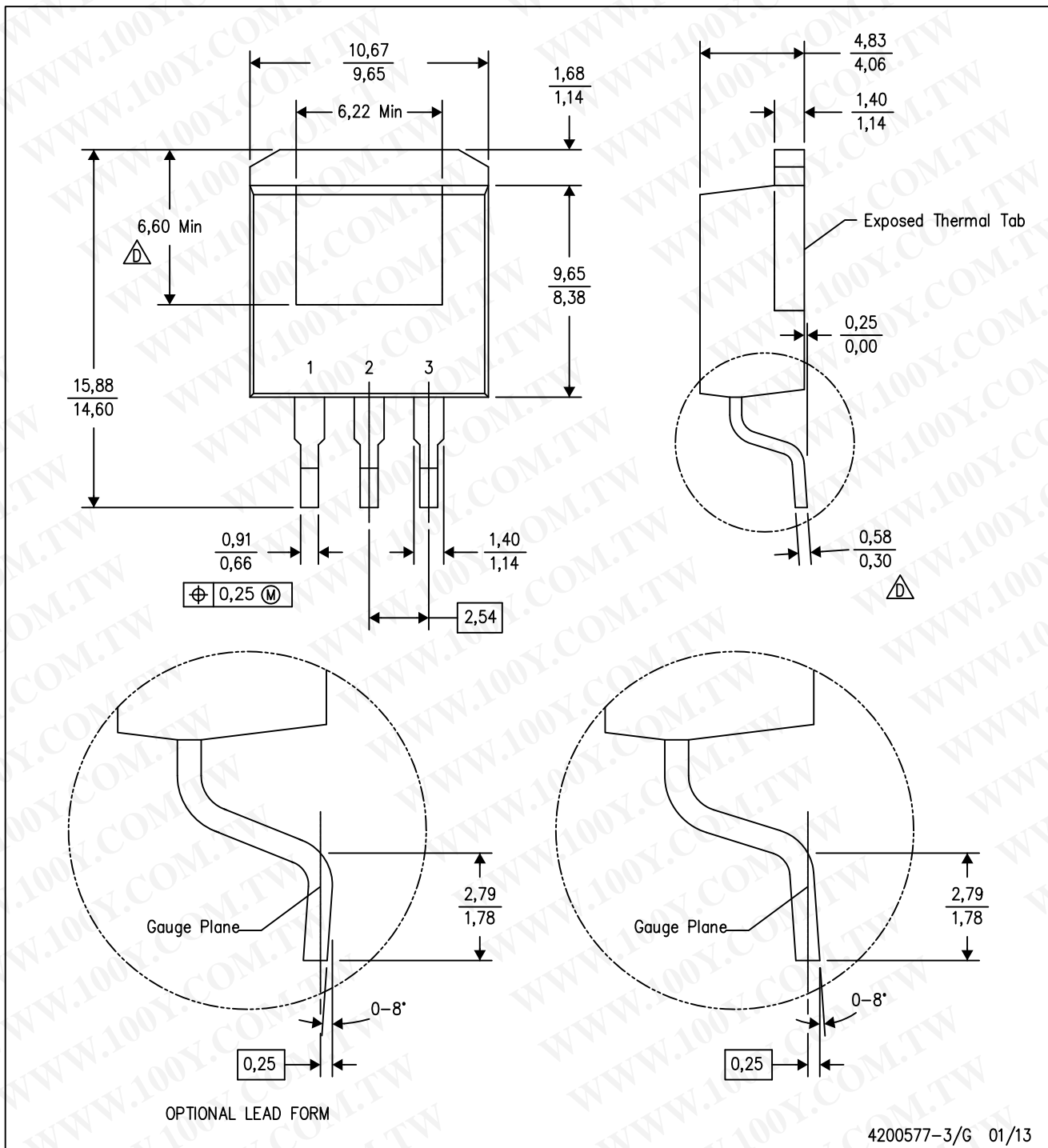
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL760M33QKVURQ1	PFM	KVU	3	2500	340.0	340.0	38.0

KTT (R-PSFM-G3)

PLASTIC FLANGE-MOUNT PACKAGE

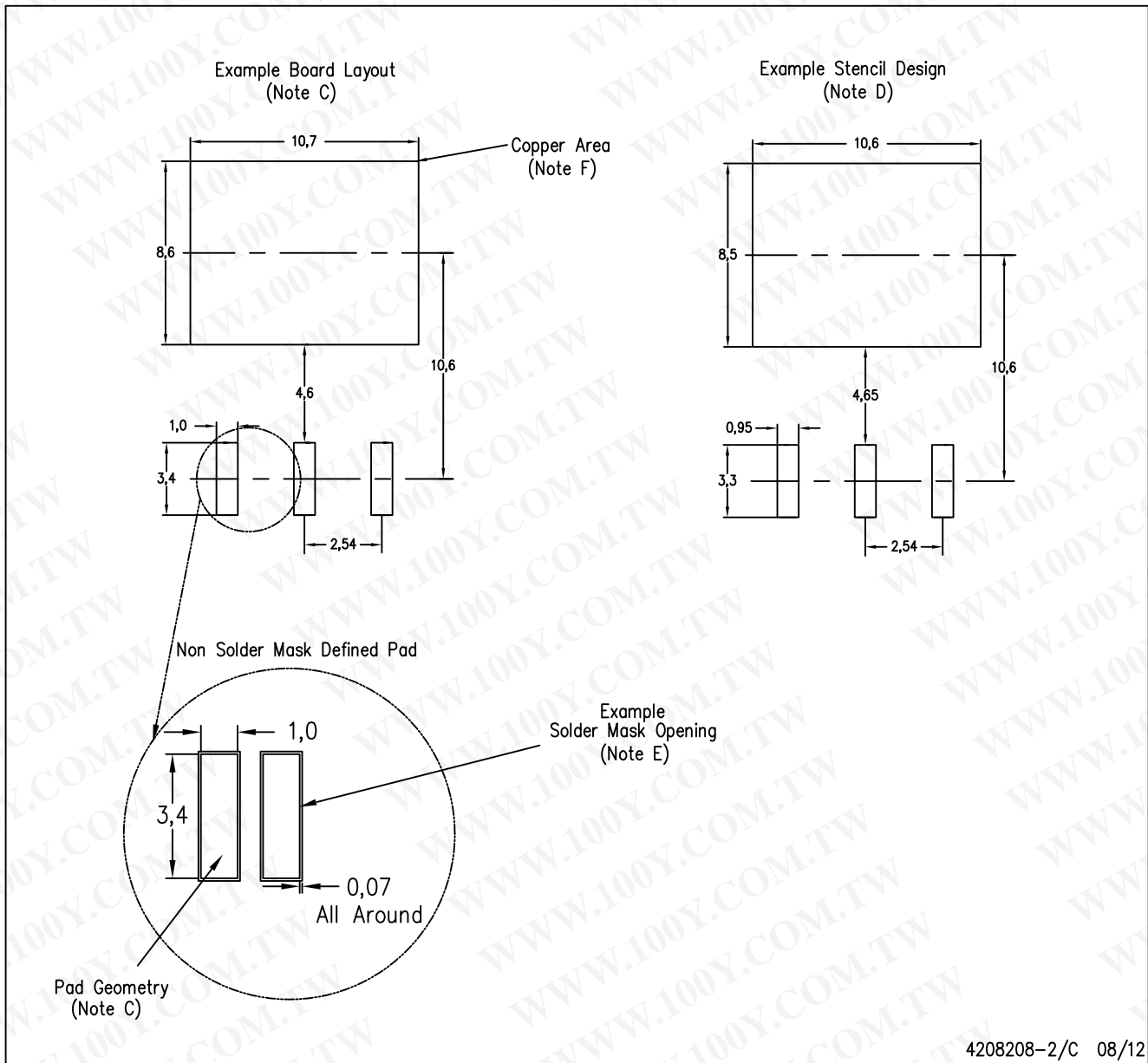


4200577-3/G 01/13

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
 - D. Falls within JEDEC TO-263 variation AA, except minimum lead thickness and minimum exposed pad length.

KTT (R-PSFM-G3)

PLASTIC FLANGE-MOUNT PACKAGE



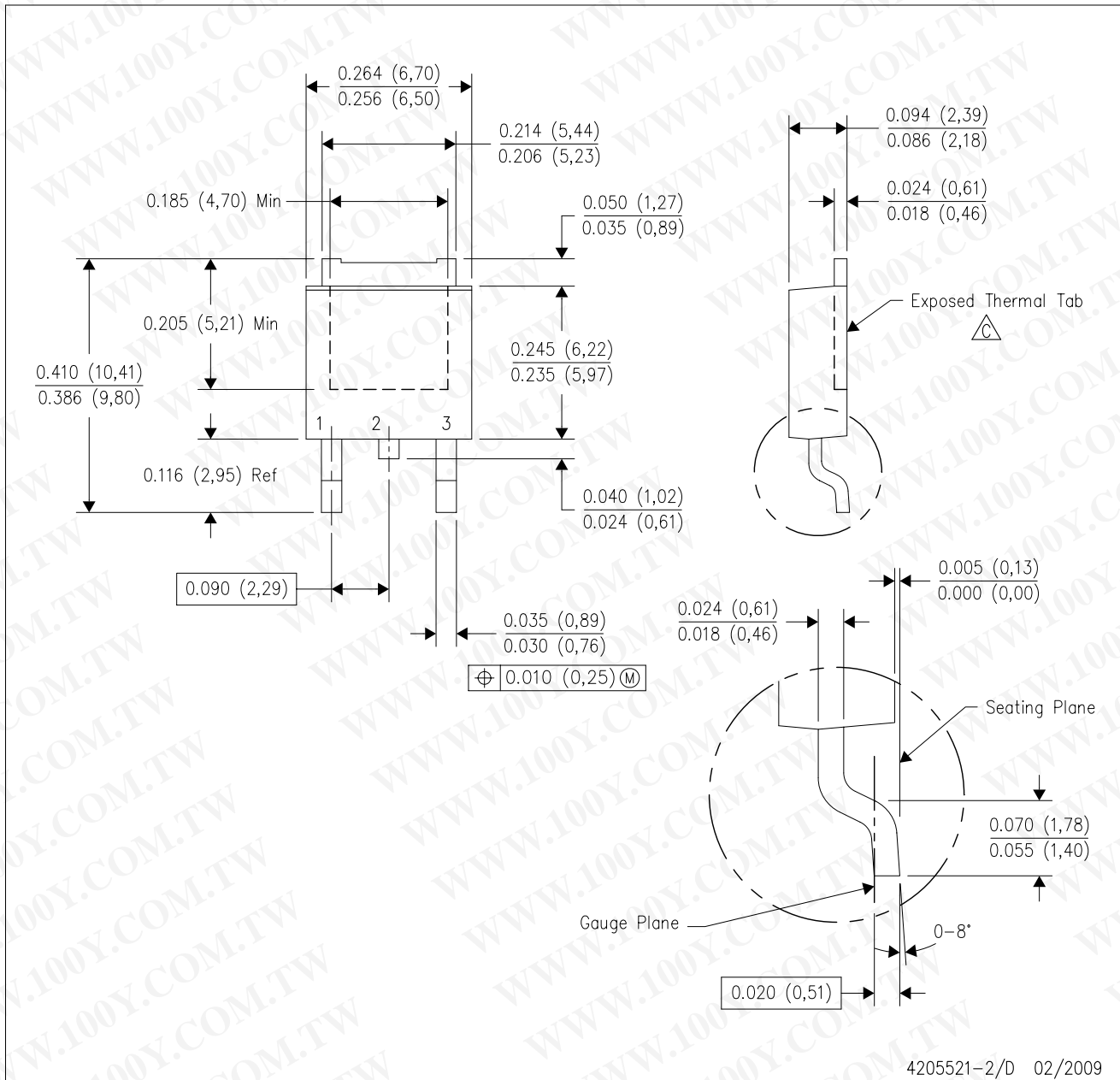
4208208-2/C 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-SM-782 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
 - F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.

MECHANICAL DATA

KVU (R-PSFM-G3)

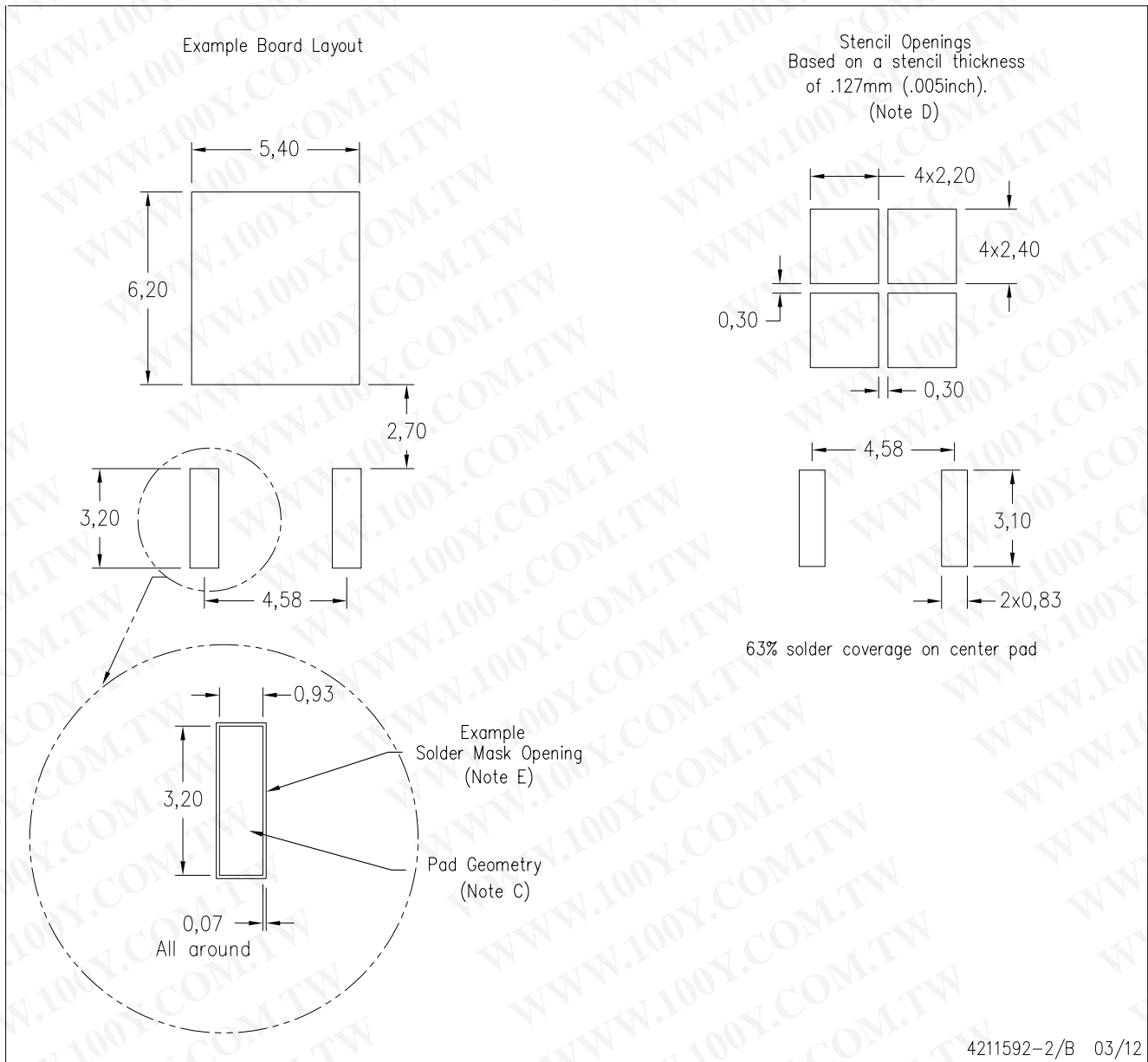
PLASTIC FLANGE-MOUNT PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. The center lead is in electrical contact with the exposed thermal tab.
 - D. Body Dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.006 (0,15) per side.
 - E. Falls within JEDEC TO-252 variation AA.

KVU (R-PSFM-G3)

PLASTIC FLANGE MOUNT PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-SM-782 is an alternate information source for PCB land pattern designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in thermal pad.

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